

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20200520000.2 Packing material change for Select Device(s) Change Notification / Sample Request

Date: June 08, 2020 **To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team SC Business Services

20200520000 Change Notification / Sample Request Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Product Change follow on the next page(s).

This change notification is to announce the addition of using ESD sealed bag for the shipping reel before placing inside the Pizza Box Visual comparison Packing beta Packing beta Pizza Box Pizza Box	PCN	CN Number: 20200520000.2 PCN Date: June 8, 2020							020				
Dec. 8, 2020 Estimated Sample Availability: Part number change Type: Decision Decision Decision Wafer Bump Site Decision Decision Wafer Bump Material Wafer Bump Material Assembly Process Deat Sheet Wafer Bump Material Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Parking/Shipping/Labeling Test Site Wafer Bump Process Parking/Shipping/Labeling Test Process Wafer Fab Site Wafer Fab Site Wafer Fab Process PCN Details Wafer Fab Process Wafer Fab Process PCN Details Wafer Fab Process PCN Details Parking/Shipping/Labeling Test Process PCN Details Wafer Fab Process PCN Details Parking/Shipping/Labeling Parking/Shipping/Labeling Test Process PCN Details Wafer Fab Process PCN Details PCN Det	Title	Packing	materi	al chan	ge for	Select D	evice(s)						
Change Type: Assembly Site Design Wafer Bump Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Design Wafer Bump Material Assembly Materials Desta Sheet Wafer Bump Process Assembly Materials Desta Sheet Wafer Bump Process Mechanical Specification Desta Site Wafer Bump Process Mechanical Specification Desta Site Wafer Fab Materials Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Materials Wafer Fab Process Wafer Fab Materials Wafer Fab Material Wafer Fab Materials Wafer Fab	Cus	tomer Conta	ct: P	CN Mana	<u>iger</u>	Dept:							
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Product Affected:							
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DRV5013ADEDBZJQ1	DRV5023AJEDBZRQ1	DRV5053CAEDBZTQ1	DRV5053PAQDBZRQ1				
DRV5013ADEDBZRQ1	DRV5023AJEDBZTQ1	DRV5053CAQDBZRQ1	DRV5053PAQDBZTQ1				
DRV5013ADEDBZTQ1	DRV5023AJQDBZRQ1	DRV5053CAQDBZTQ1	DRV5053RAEDBZRQ1				
DRV5013ADQDBZRQ1	DRV5023AJQDBZTQ1	DRV5053EAEDBZRQ1	DRV5053RAEDBZTQ1				
DRV5013ADQDBZTQ1	DRV5023BIEDBZRQ1	DRV5053EAEDBZTQ1	DRV5053RAQDBZRQ1				
DRV5013AGEDBZRQ1	DRV5023BIEDBZTQ1	DRV5053EAQDBZRQ1	DRV5053RAQDBZTQ1				
DRV5013AGEDBZTQ1	DRV5023BIQDBZRQ1	DRV5053EAQDBZTQ1	DRV5053VAEDBZRQ1				
DRV5013AGQDBZRQ1	DRV5023BIQDBZTQ1	DRV5053OAEDBZRQ1	DRV5053VAEDBZTQ1				
DRV5013AGQDBZTQ1	DRV5033AJEDBZRQ1	DRV5053OAEDBZTQ1	DRV5053VAQDBZRQ1				
DRV5013BCEDBZRQ1	DRV5033AJEDBZTQ1	DRV5053OAQDBZRQ1	DRV5053VAQDBZTQ1				
DRV5013BCEDBZTQ1	DRV5033AJQDBZRQ1	DRV5053OAQDBZTQ1	SN74AUP2G00QDCURQ1				
DRV5013BCQDBZRQ1	DRV5033AJQDBZTQ1	DRV5053PAEDBZRQ1	TPD2E001IDRLRQ1				
DRV5013BCQDBZTQ1	DRV5053CAEDBZRQ1	DRV5053PAEDBZTQ1					

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin_team@list.ti.com

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